

Filed:

December 18, 2001

) AFTER FINAL

For:

SEMICONDUCTOR DEVICE

Docket No.:

**KAN 137** 

February 14, 2003

**BOX: AF** 

Assistant Commissioner of Patents and Trademarks Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on November 18, 2002, please amend the above-identified application as follows:

## **IN THE CLAIMS:**

Please amend the following claim:

1. (Twice Amended) A semiconductor device, comprising:

a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, said electrode pads being disposed to surround an area of the circuit forming surface;

a semiconductor element mounted within the area of the circuit forming surface;

a plurality of adhesive lines adapted for use as reference lines, said adhesive lines being disposed under the semiconductor element and on the circuit forming surface, and being respectively provided at positions corresponding to at least three

Piges charge any furthe fee to our D posit Account No. 18-0002